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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	3456
Number of Logic Elements/Cells	15552
Total RAM Bits	294912
Number of I/O	316
Number of Gates	985882
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	432-LBGA Exposed Pad, Metal
Supplier Device Package	432-MBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv600e-7bg432c

forces a storage element into the initialization state specified for it in the configuration. BY forces it into the opposite state. Alternatively, these signals can be configured to operate asynchronously. All of the control signals are independently invertible, and are shared by the two flip-flops within the slice.

Additional Logic

The F5 multiplexer in each slice combines the function generator outputs. This combination provides either a function generator that can implement any 5-input function, a 4:1 multiplexer, or selected functions of up to nine inputs.

Similarly, the F6 multiplexer combines the outputs of all four function generators in the CLB by selecting one of the F5-multiplexer outputs. This permits the implementation of any 6-input function, an 8:1 multiplexer, or selected functions of up to 19 inputs.

Each CLB has four direct feedthrough paths, two per slice. These paths provide extra data input lines or additional local routing that does not consume logic resources.

Arithmetic Logic

Dedicated carry logic provides fast arithmetic carry capability for high-speed arithmetic functions. The Virtex-E CLB supports two separate carry chains, one per Slice. The height of the carry chains is two bits per CLB.

The arithmetic logic includes an XOR gate that allows a 2-bit full adder to be implemented within a slice. In addition, a dedicated AND gate improves the efficiency of multiplier implementation. The dedicated carry path can also be used to cascade function generators for implementing wide logic functions.

BUFTs

Each Virtex-E CLB contains two 3-state drivers (BUFTs) that can drive on-chip buses. See **Dedicated Routing**. Each Virtex-E BUFT has an independent 3-state control pin and an independent input pin.

Block SelectRAM

Virtex-E FPGAs incorporate large block SelectRAM memories. These complement the Distributed SelectRAM memories that provide shallow RAM structures implemented in CLBs.

Block SelectRAM memory blocks are organized in columns, starting at the left (column 0) and right outside edges and inserted every 12 CLB columns (see notes for smaller devices). Each memory block is four CLBs high, and each memory column extends the full height of the chip, immediately adjacent (to the right, except for column 0) of the CLB column locations indicated in Table 3.

Table 3: **CLB/Block RAM Column Locations**

XCV Device /Col.	0	12	24	36	48	60	72	84	96	108	120	138	156
50E	Columns 0, 6, 18, & 24												
100E	Columns 0, 12, 18, & 30												
200E	Columns 0, 12, 30, & 42												
300E	√	√		√	√								
400E	√	√			√	√							
600E	√	√	√		√	√	√						
1000E	√	√	√				√	√	√				
1600E	√	√	√	√			√	√	√	√			
2000E	√	√	√	√				√	√	√	√		
2600E	√	√	√	√					√	√	√	√	
3200E	√	√	√	√						√	√	√	√

Table 4 shows the amount of block SelectRAM memory that is available in each Virtex-E device.

Table 4: **Virtex-E Block SelectRAM Amounts**

Virtex-E Device	# of Blocks	Block SelectRAM Bits
XCV50E	16	65,536
XCV100E	20	81,920
XCV200E	28	114,688
XCV300E	32	131,072
XCV400E	40	163,840
XCV600E	72	294,912
XCV1000E	96	393,216
XCV1600E	144	589,824
XCV2000E	160	655,360
XCV2600E	184	753,664
XCV3200E	208	851,968

As illustrated in Figure 6, each block SelectRAM cell is a fully synchronous dual-ported (True Dual Port) 4096-bit RAM with independent control signals for each port. The data widths of the two ports can be configured independently, providing built-in bus-width conversion.

3. At the rising edge of CCLK: If BUSY is Low, the data is accepted on this clock. If BUSY is High (from a previous write), the data is not accepted. Acceptance instead occurs on the first clock after BUSY goes Low, and the data must be held until this has happened.
4. Repeat steps 2 and 3 until all the data has been sent.
5. De-assert $\overline{CS}$ and $\overline{WRITE}$.

Table 11: **SelectMAP Write Timing Characteristics**

	Description		Symbol		Units
CCLK	D_{0-7} Setup/Hold	1/2	T_{SMDCC}/T_{SMCCD}	5.0 / 1.7	ns, min
	$\overline{CS}$ Setup/Hold	3/4	T_{SMCSCC}/T_{SMCCCS}	7.0 / 1.7	ns, min
	$\overline{WRITE}$ Setup/Hold	5/6	T_{SMCCW}/T_{SMWCC}	7.0 / 1.7	ns, min
	BUSY Propagation Delay	7	T_{SMCKBY}	12.0	ns, max
	Maximum Frequency		F_{CC}	66	MHz, max
	Maximum Frequency with no handshake		F_{CCNH}	50	MHz, max

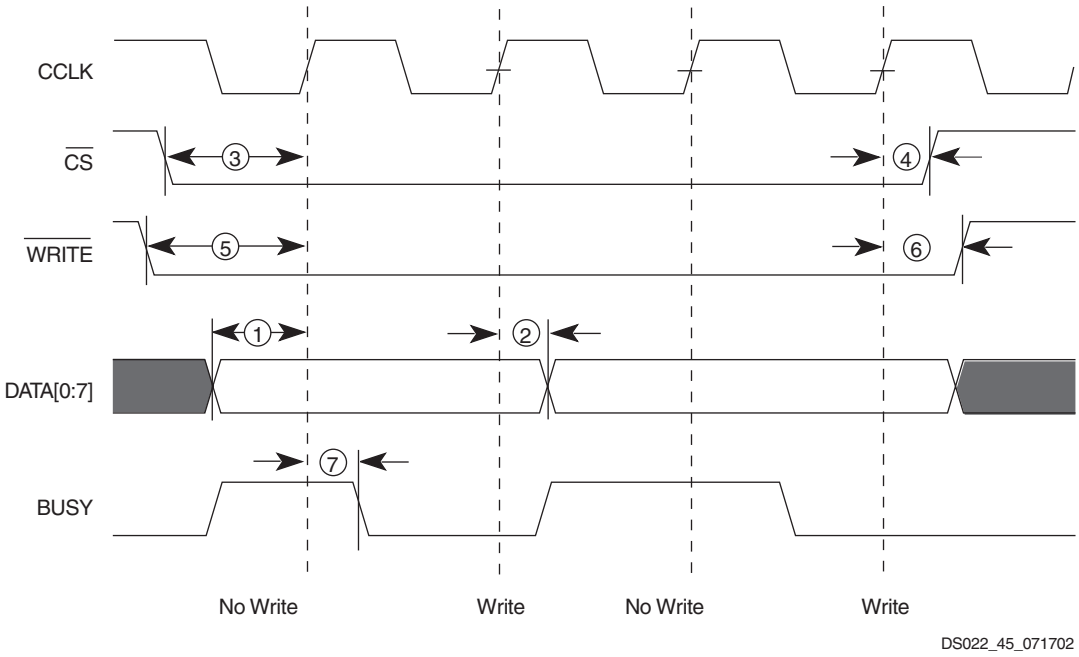

Figure 17: **Write Operations**

A flowchart for the write operation is shown in Figure 18. Note that if CCLK is slower than f_{CCNH}, the FPGA never asserts BUSY, In this case, the above handshake is unnecessary, and data can simply be entered into the FPGA every CCLK cycle.

Abort

During a given assertion of $\overline{CS}$, the user cannot switch from a write to a read, or vice-versa. This action causes the current packet command to be aborted. The device remains BUSY until the aborted operation has completed. Following an abort, data is assumed to be unaligned to word boundaries, and the FPGA requires a new synchronization word prior to accepting any new packets.

To initiate an abort during a write operation, de-assert $\overline{WRITE}$. At the rising edge of CCLK, an abort is initiated, as shown in Figure 19.

Useful Application Examples

The Virtex-E DLL can be used in a variety of creative and useful applications. The following examples show some of the more common applications. The Verilog and VHDL example files are available at:

ftp://ftp.xilinx.com/pub/applications/xapp/xapp132.zip

Standard Usage

The circuit shown in Figure 27 resembles the BUFGDLL macro implemented to provide access to the RST and LOCKED pins of the CLKDLL.

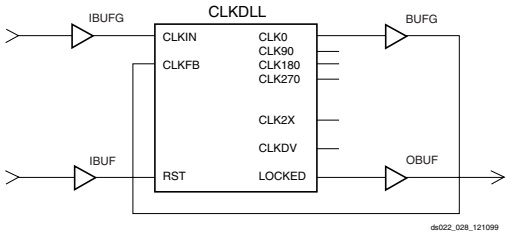

Figure 27: **Standard DLL Implementation**

Board Level Deskew of Multiple Non-Virtex-E Devices

The circuit shown in Figure 28 can be used to deskew a system clock between a Virtex-E chip and other non-Virtex-E chips on the same board. This application is commonly used when the Virtex-E device is used in conjunction with other standard products such as SRAM or DRAM devices. While designing the board level route, ensure that the return net delay to the source equals the delay to the other chips involved.

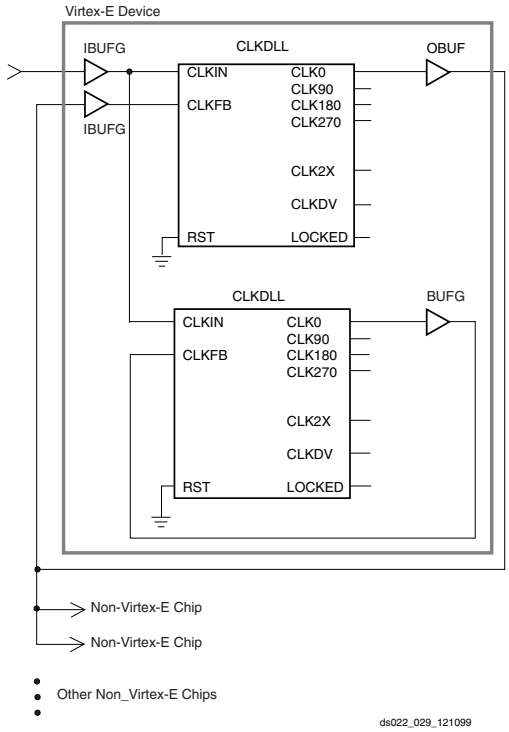

Figure 28: **DLL Deskew of Board Level Clock**

Board-level deskew is not required for low-fanout clock networks. It is recommended for systems that have fanout limitations on the clock network, or if the clock distribution chip cannot handle the load.

Do not use the DLL output clock signals until after activation of the LOCKED signal. Prior to the activation of the LOCKED signal, the DLL output clocks are not valid and can exhibit glitches, spikes, or other spurious movement.

The dll_mirror_1 files in the **xapp132.zip** file show the VHDL and Verilog implementation of this circuit.

Deskew of Clock and Its 2x Multiple

The circuit shown in Figure 29 implements a 2x clock multiplier and also uses the CLK0 clock output with a zero ns skew between registers on the same chip. Alternatively, a clock divider circuit can be implemented using similar connections.

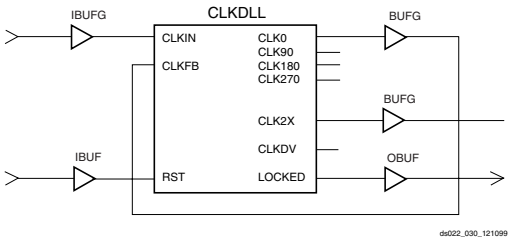

Figure 29: **DLL Deskew of Clock and 2x Multiple**

Because any single DLL can access only two BUFGs at most, any additional output clock signals must be routed from the DLL in this example on the high speed backbone routing.

The dll_2x files in the **xapp132.zip** file show the VHDL and Verilog implementation of this circuit.

Virtex-E 4x Clock

Two DLLs located in the same half-edge (top-left, top-right, bottom-right, bottom-left) can be connected together, without using a BUFG between the CLKDLLs, to generate a 4x clock as shown in Figure 30. Virtex-E devices, like the Virtex devices, have four clock networks that are available for internal deskewing of the clock. Each of the eight DLLs have access to two of the four clock networks. Although all the DLLs can be used for internal deskewing, the presence of two GCLKBUFs on the top and two on the bottom indicate that only two of the four DLLs on the top (and two of the four DLLs on the bottom) can be used for this purpose.

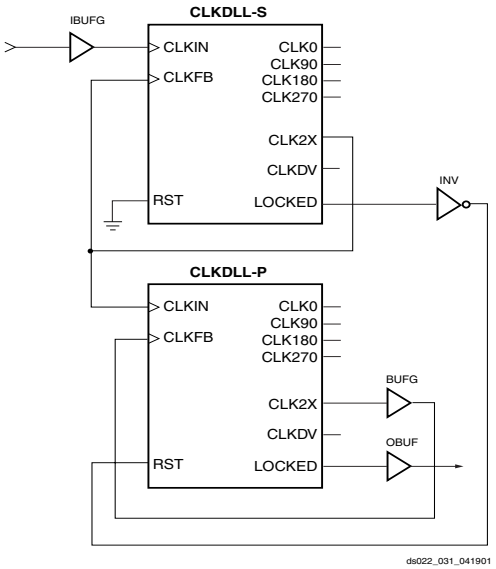

Figure 30: **DLL Generation of 4x Clock in Virtex-E Devices**

The dll_4xe files in the xapp132.zip file show the DLL implementation in Verilog for Virtex-E devices. These files can be found at:

ftp://ftp.xilinx.com/pub/applications/xapp/xapp132.zip

Using Block SelectRAM+ Features

The Virtex FPGA Series provides dedicated blocks of on-chip, true dual-read/write port synchronous RAM, with 4096 memory cells. Each port of the block SelectRAM+ memory can be independently configured as a read/write port, a read port, a write port, and can be configured to a specific data width. The block SelectRAM+ memory offers new capabilities allowing the FPGA designer to simplify designs.

Operating Modes

VIrtex-E block SelectRAM+ memory supports two operating modes:

- Read Through
- Write Back

Read Through (one clock edge)

The read address is registered on the read port clock edge and data appears on the output after the RAM access time. Some memories might place the latch/register at the outputs, depending on whether a faster clock-to-out versus set-up time is desired. This is generally considered to be an inferior solution, since it changes the read operation to an asynchronous function with the possibility of missing an address/control line transition during the generation of the read pulse clock.

Write Back (one clock edge)

The write address is registered on the write port clock edge and the data input is written to the memory and mirrored on the output.

Block SelectRAM+ Characteristics

- All inputs are registered with the port clock and have a set-up to clock timing specification.
- All outputs have a read through or write back function depending on the state of the port WE pin. The outputs relative to the port clock are available after the clock-to-out timing specification.
- The block SelectRAMs are true SRAM memories and do not have a combinatorial path from the address to the output. The LUT SelectRAM+ cells in the CLBs are still available with this function.
- The ports are completely independent from each other (*i.e.,* clocking, control, address, read/write function, and data width) without arbitration.
- A write operation requires only one clock edge.
- A read operation requires only one clock edge.

The output ports are latched with a self timed circuit to guarantee a glitch free read. The state of the output port does not change until the port executes another read or write operation.

Library Primitives

Figure 31 and Figure 32 show the two generic library block SelectRAM+ primitives. Table 14 describes all of the available primitives for synthesis and simulation.

Initialization in Verilog and Synopsys

The block SelectRAM+ structures can be initialized in Verilog for both simulation and synthesis for inclusion in the EDIF output file. The simulation of the Verilog code uses a defparam to pass the initialization. The Synopsys FPGA compiler does not presently support defparam. The initialization values instead attach as attributes to the RAM by a built-in Synopsys dc_script. The translate_off statement stops synthesis translation of the defparam statements. The following code illustrates a module that employs these techniques.

Design Examples

Creating a 32-bit Single-Port RAM

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single port, 128 deep by 32-bit wide RAM to be created using a single block SelectRAM+ cell as shown in Figure 35.

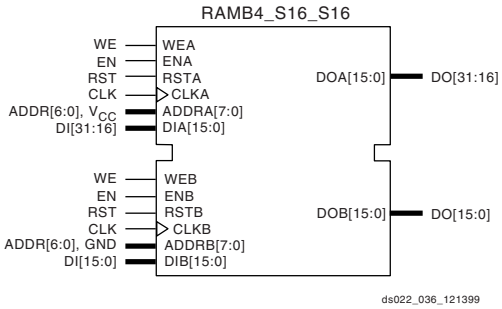

Figure 35: **Single Port 128 x 32 RAM**

Interleaving the memory space, setting the LSB of the address bus of Port A to 1 (V_{CC}), and the LSB of the address bus of Port B to 0 (GND), allows a 32-bit wide single port RAM to be created.

Creating Two Single-Port RAMs

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single RAM to be split into two single port memories of 2K bits each as shown in Figure 36.

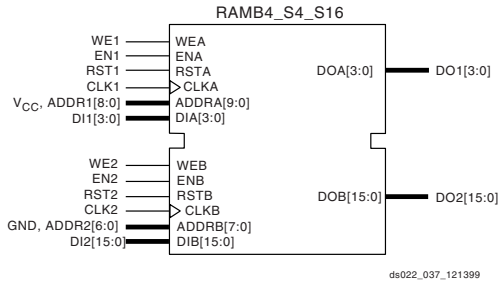

Figure 36: **512 x 4 RAM and 128 x 16 RAM**

In this example, a 512K x 4 RAM (Port A) and a 128 x 16 RAM (Port B) are created out of a single block SelectRAM+. The address space for the RAM is split by fixing the MSB of Port A to 1 (V_{CC}) for the upper 2K bits and the MSB of Port B to 0 (GND) for the lower 2K bits.

Block Memory Generation

The CoreGen program generates memory structures using the block SelectRAM+ features. This program outputs VHDL or Verilog simulation code templates and an EDIF file for inclusion in a design.

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUF placement restrictions require that any differential amplifier input signals within a bank be of the same standard. How to specify a specific location for the IBUF via the LOC property is described below. Table 19 summarizes the Virtex-E input standards compatibility requirements.

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element by default activates to ensure a zero hold-time requirement. The NODELAY=TRUE property overrides this default.

When the IBUF does not drive a flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

Table 19: **Xilinx Input Standards Compatibility Requirements**

Rule 1	Standards with the same input V_{CCO}, output V_{CCO}, and V_{REF} can be placed within the same bank.

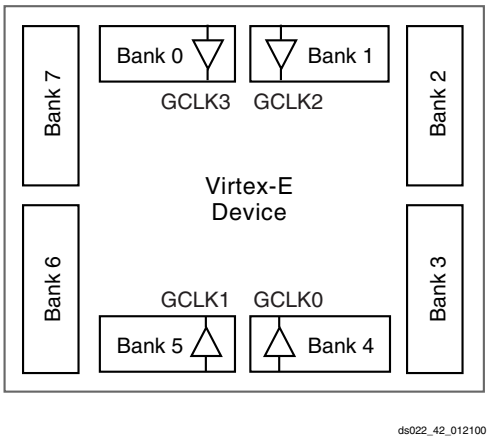

Figure 38: **Virtex-E I/O Banks**

IBUFG

Signals used as high fanout clock inputs to the Virtex-E device should drive a global clock input buffer (IBUFG) via an external input port in order to take advantage of one of the four dedicated global clock distribution networks. The output of the IBUFG should only drive a CLKDLL, CLKDLLHF, or BUFG symbol. The generic Virtex-E IBUFG symbol appears in Figure 39.

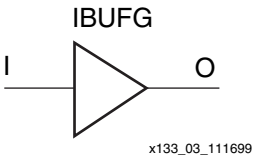

Figure 39: **Virtex-E Global Clock Input Buffer (IBUFG) Symbol**

The extension to the base name determines which I/O standard is used by the IBUFG. With no extension specified for the generic IBUFG symbol, the assumed standard is LVTTL.

The following list details variations of the IBUFG symbol.

- IBUFG
- IBUFG_LVCMOS2
- IBUFG_PCI33_3
- IBUFG_PCI66_3
- IBUFG_GTL
- IBUFG_GTLP
- IBUFG_HSTL_I
- IBUFG_HSTL_III
- IBUFG_HSTL_IV
- IBUFG_SSTL3_I
- IBUFG_SSTL3_II
- IBUFG_SSTL2_I
- IBUFG_SSTL2_II
- IBUFG_CTT
- IBUFG_AGP
- IBUFG_LVCMOS18
- IBUFG_LVDS
- IBUFG_LVPECL

When the IBUFG symbol supports an I/O standard that requires a differential amplifier input, the IBUFG automatically configures as a differential amplifier input buffer. The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF}.

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUFG placement restrictions require any differential amplifier input signals within a bank be of the same standard. The LOC property can specify a location for the IBUFG.

As an added convenience, the BUFGP can be used to instantiate a high fanout clock input. The BUFGP symbol

LVDS

Depending on whether the device is transmitting an LVDS signal or receiving an LVDS signal, there are two different circuits used for LVDS termination. A sample circuit illustrating a valid termination technique for transmitting LVDS signals appears in Figure 54. A sample circuit illustrating a valid termination for receiving LVDS signals appears in Figure 55. Table 38 lists DC voltage specifications. Further information on the specific termination resistor packs shown can be found on Table 40.

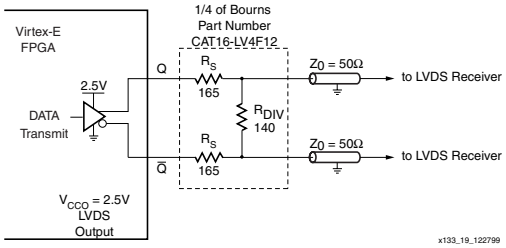

Figure 54: **Transmitting LVDS Signal Circuit**

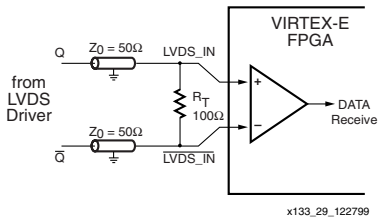

Figure 55: **Receiving LVDS Signal Circuit**

Table 38: **LVDS Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.375	2.5	2.625
V_{ICM}(2)	0.2	1.25	2.2
V_{OCM}(1)	1.125	1.25	1.375
V_{IDIFF} (1)	0.1	0.35	-
V_{ODIFF} (1)	0.25	0.35	0.45
V_{OH}(1)	1.25	-	-
V_{OL}(1)	-	-	1.25

Notes:
1. Measured with a 100 Ω resistor across Q and $\overline{Q}$.
2. Measured with a differential input voltage = +/– 350 mV.

LVPECL

Depending on whether the device is transmitting or receiving an LVPECL signal, two different circuits are used for LVPECL termination. A sample circuit illustrating a valid termination technique for transmitting LVPECL signals appears in Figure 56. A sample circuit illustrating a valid termination for receiving LVPECL signals appears in Figure 57. Table 39 lists DC voltage specifications. Further information on the specific termination resistor packs shown can be found on Table 40.

Table 39: **LVPECL Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	1.49	-	2.72
V_{IL}	0.86	-	2.125
V_{OH}	1.8	-	-
V_{OL}	-	-	1.57

Notes:
1. For more detailed information, see **DS022-3**: *Virtex-E 1.8V FPGA DC and Switching Characteristics*, Module 3, LVPECL DC Specifications section.

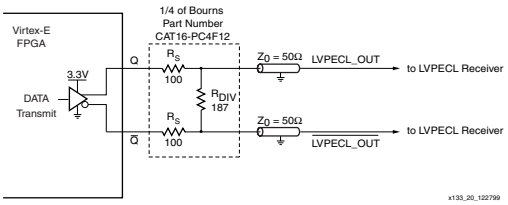

Figure 56: **Transmitting LVPECL Signal Circuit**

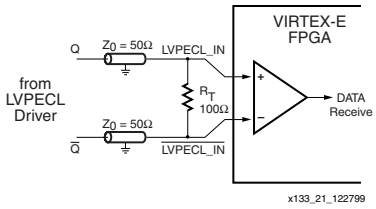

Figure 57: **Receiving LVPECL Signal Circuit**

Termination Resistor Packs

Resistor packs are available with the values and the configuration required for LVDS and LVPECL termination from Bourns, Inc., as listed in Table. For pricing and availability, please contact Bourns directly at **http://www.bourns.com**.

Table 40: **Bourns LVDS/LVPECL Resistor Packs**

Part Number	I/O Standard	Term. for:	Pairs/ Pack	Pins
CAT16–LV2F6	LVDS	Driver	2	8
CAT16–LV4F12	LVDS	Driver	4	16
CAT16–PC2F6	LVPECL	Driver	2	8
CAT16–PC4F12	LVPECL	Driver	4	16
CAT16–PT2F2	LVDS/LVPECL	Receiver	2	8
CAT16–PT4F4	LVDS/LVPECL	Receiver	4	16

LVDS Design Guide

The SelectI/O library elements have been expanded for Virtex-E devices to include new LVDS variants. At this time all of the cells might not be included in the Synthesis libraries. The 2.1i-Service Pack 2 update for Alliance and Foundation software includes these cells in the VHDL and Verilog libraries. It is necessary to combine these cells to create the P-side (positive) and N-side (negative) as described in the input, output, 3-state and bidirectional sections.

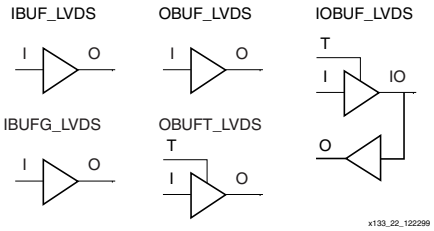

Figure 58: **LVDS elements**

Creating LVDS Global Clock Input Buffers

Global clock input buffers can be combined with adjacent IOBs to form LVDS clock input buffers. P-side is the GCLKPAD location; N-side is the adjacent IO_LVDS_DLL site.

Table 41: **Global Clock Input Buffer Pair Locations**

	GCLK 3		GCLK 2		GCLK 1		GCLK 0	
Pkg	P	N	P	N	P	N	P	N
CS144	A6	C6	A7	B7	M7	M6	K7	N8
PQ240	P213	P215	P210	P209	P89	P87	P92	P93
HQ240	P213	P215	P210	P209	P89	P87	P92	P93
BG352	D14	A15	B14	A13	AF14	AD14	AE13	AC13
BG432	D17	C17	A16	B16	AK16	AL17	AL16	AH15
BG560	A17	C18	D17	E17	AJ17	AM18	AL17	AM17
FG256	B8	A7	C9	A8	R8	T8	N8	N9
FG456	C11	B11	A11	D11	YII	AA11	W12	U12
FG676	E13	B13	C13	F14	AB13	AF13	AA14	AC14
FG680	A20	C22	D21	A19	AU22	AT22	AW19	AT21
FG860	C22	A22	B22	D22	AY22	AW21	BA22	AW20
FG900	C15	A15	E15	E16	AK16	AH16	AJ16	AF16
FG1156	E17	C17	D17	J18	AI19	AL17	AH18	AM18

HDL Instantiation

Only one global clock input buffer is required to be instantiated in the design and placed on the correct GCLKPAD location. The N-side of the buffer is reserved and no other IOB is allowed to be placed on this location.

In the physical device, a configuration option is enabled that routes the pad wire to the differential input buffer located in the GCLKIOB. The output of this buffer then drives the output of the GCLKIOB cell. In EPIC it appears that the second buffer is unused. Any attempt to use this location for another purpose leads to a DRC error in the software.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_external),
.O(clk_internal));
```

Location constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET clk_external LOC = GCLKPAD3;
```

GCLKPAD3 can also be replaced with the package pin name such as D17 for the BG432 package.

Virtex-E Data Sheet

The Virtex-E Data Sheet contains the following modules:

- DS022-1, Virtex-E 1.8V FPGAs:
  Introduction and Ordering Information (Module 1)
- DS022-2, Virtex-E 1.8V FPGAs:
  Functional Description (Module 2)
- DS022-3, Virtex-E 1.8V FPGAs:
  DC and Switching Characteristics (Module 3)
- DS022-4, Virtex-E 1.8V FPGAs:
  Pinout Tables (Module 4)

Virtex-E Pin Definitions

Pin Name	Dedicated Pin	Direction	Description
GCK0, GCK1, GCK2, GCK3	Yes	Input	Clock input pins that connect to Global Clock Buffers.
M0, M1, M2	Yes	Input	Mode pins are used to specify the configuration mode.
CCLK	Yes	Input or Output	The configuration Clock I/O pin: it is an input for SelectMAP and slave-serial modes, and output in master-serial mode. After configuration, it is input only, logic level = Don't Care.
PROGRAM	Yes	Input	Initiates a configuration sequence when asserted Low.
DONE	Yes	Bidirectional	Indicates that configuration loading is complete, and that the start-up sequence is in progress. The output can be open drain.
INIT	No	Bidirectional (Open-drain)	When Low, indicates that the configuration memory is being cleared. The pin becomes a user I/O after configuration.
BUSY/DOUT	No	Output	In SelectMAP mode, BUSY controls the rate at which configuration data is loaded. The pin becomes a user I/O after configuration unless the SelectMAP port is retained. In bit-serial modes, DOUT provides preamble and configuration data to downstream devices in a daisy-chain. The pin becomes a user I/O after configuration.
D0/DIN, D1, D2, D3, D4, D5, D6, D7	No	Input or Output	In SelectMAP mode, D0-7 are configuration data pins. These pins become user I/Os after configuration unless the SelectMAP port is retained. In bit-serial modes, DIN is the single data input. This pin becomes a user I/O after configuration.
WRITE	No	Input	In SelectMAP mode, the active-low Write Enable signal. The pin becomes a user I/O after configuration unless the SelectMAP port is retained.
CS	No	Input	In SelectMAP mode, the active-low Chip Select signal. The pin becomes a user I/O after configuration unless the SelectMAP port is retained.
TDI, TDO, TMS, TCK	Yes	Mixed	Boundary-scan Test-Access-Port pins, as defined in IEEE1149.1.
DXN, DXP	Yes	N/A	Temperature-sensing diode pins. (Anode: DXP, cathode: DXN)
V_{CCINT}	Yes	Input	Power-supply pins for the internal core logic.
V_{CCO}	Yes	Input	Power-supply pins for the output drivers (subject to banking rules)
V_{REF}	No	Input	Input threshold voltage pins. Become user I/Os when an external threshold voltage is not needed (subject to banking rules).
GND	Yes	Input	Ground

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P210	GCK2	1
P209	IO_LVDS_DLL_L6P	1
P208	IO_VREF	1
P207	VCCO	1
P206	IO_L7N_Y	1
P205	IO_VREF_L7P_Y	1
P204	GND	NA
P203	IO_L8N_Y	1
P202	IO_L8P_Y	1
P201[1]	IO_VREF	1
P200	IO_L9N_YY	1
P199	IO_L9P_YY	1
P198	VCCINT	NA
P197	VCCO	1
P196	GND	NA
P195	IO_L10N_YY	1
P194	IO_VREF_L10P_YY	1
P193	IO_VREF	1
P192	IO_L11N_YY	1
P191	IO_VREF_L11P_YY	1
P190	GND	NA
P189	IO_L12N_YY	1
P188	IO_L12P_YY	1
P187	IO_VREF_L13N	1
P186	IO_L13P	1
P185	IO_WRITE_L14N_YY	1
P184	IO_CS_L14P_YY	1
P183	TDI	NA
P182	GND	NA
P181	TDO	2
P180	VCCO	1
P179	CCLK	2
P178	IO_DOUT_BUSY_L15P_YY	2
P177	IO_DIN_D0_L15N_YY	2
P176	VCCO	2
P175	IO_VREF	2

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P174	IO_L16P_Y	2
P173	IO_L16N_Y	2
P172	GND	NA
P171	IO_VREF_L17P_Y	2
P170	IO_L17N_Y	2
P169	IO_VREF	2
P168	IO_VREF_L18P_Y	2
P167	IO_D1_L18N_Y	2
P166	GND	NA
P165	VCCO	2
P164	VCCINT	NA
P163	IO_D2_L19P_YY	2
P162	IO_L19N_YY	2
P161[1]	IO_VREF	2
P160	IO_L20P_Y	2
P159	IO_L20N_Y	2
P158	GND	NA
P157	IO_VREF_L21P_Y	2
P156	IO_D3_L21N_Y	2
P155	IO_L22P_Y	2
P154	IO_VREF_L22N_Y	2
P153	IO_L23P_YY	2
P152	IO_L23N_YY	2
P151	GND	NA
P150	VCCO	2
P149	IO	3
P148	VCCINT	NA
P147	IO_VREF	3
P146	VCCO	3
P145	IO_D4_L24P_Y	3
P144	IO_VREF_L24N_Y	3
P143	GND	NA
P142	IO_L25P_Y	3
P141	IO_L25N_Y	3
P140[1]	IO_VREF	3
P139	IO_L26P_YY	3

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
1	IO_L23P_Y	A17
1	IO_L24N_YY	B17
1	IO_VREF_L24P_YY	A18
1	IO_L25N_YY	D16
1	IO_L25P_YY	C17
1	IO_L26N_YY	B18
1	IO_VREF_L26P_YY	A19
1	IO_L27N_YY	D17
1	IO_L27P_YY	C18
1	IO_WRITE_L28N_YY	A20
1	IO_CS_L28P_YY	C19
2	IO	D18[1]
2	IO	E19[1]
2	IO	E20
2	IO	F20
2	IO	G21
2	IO	G22[1]
2	IO	J22
2	IO	L19[1]
2	IO_D3	K20
2	IO_DOUT_BUSY_L29P_YY	C21
2	IO_DIN_D0_L29N_YY	D20
2	IO_L30P_YY	C22
2	IO_L30N_YY	D21
2	IO_VREF_L31P_YY	D22
2	IO_L31N_YY	E21
2	IO_L32P_YY	E22
2	IO_L32N_YY	F18
2	IO_VREF_L33P_YY	F21
2	IO_L33N_YY	F19
2	IO_L34P_Y	F22
2	IO_L34N_Y	G19
2	IO_L35P_Y	G20
2	IO_L35N_Y	G18
2	IO_VREF_L36P_Y	H18
2	IO_D1_L36N_Y	H22

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
2	IO_D2_L37P_YY	H20
2	IO_L37N_YY	H19
2	IO_L38P_YY	H21
2	IO_L38N_YY	J19
2	IO_L39P_YY	J18
2	IO_L39N_YY	J20
2	IO_L40P_Y	K18
2	IO_L40N_Y	J21
2	IO_L41P	K22
2	IO_VREF_L41N	K21
2	IO_L42P_Y	K19
2	IO_L42N_Y	L22
2	IO_L43P_YY	L21
2	IO_L43N_YY	L18
2	IO_L44P_YY	L17
2	IO_L44N_YY	L20
3	IO	M21[1]
3	IO	P22
3	IO	R20[1]
3	IO	R22
3	IO	T19
3	IO	U18[1]
3	IO	V20
3	IO	V21
3	IO	Y22[1]
3	IO_L45P_YY	M18
3	IO_L45N_YY	M20
3	IO_L46P_Y	M19
3	IO_L46N_Y	M17
3	IO_D4_L47P_Y	N22
3	IO_VREF_L47N_Y	N21
3	IO_L48P_YY	N20
3	IO_L48N_YY	N18
3	IO_L49P_YY	N19
3	IO_L49N_YY	P21
3	IO_L50P_YY	P20

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
NA	GND	M14
NA	GND	M13
NA	GND	M12
NA	GND	M11
NA	GND	M10
NA	GND	M9
NA	GND	L14
NA	GND	L13
NA	GND	L12
NA	GND	L11
NA	GND	L10
NA	GND	L9
NA	GND	K14
NA	GND	K13
NA	GND	K12
NA	GND	K11
NA	GND	K10
NA	GND	K9
NA	GND	J14
NA	GND	J13
NA	GND	J12
NA	GND	J11
NA	GND	J10
NA	GND	J9
NA	GND	C20
NA	GND	C3
NA	GND	B21
NA	GND	B2
NA	GND	A22
NA	GND	A1

Note 1: NC in the XCV200E device.

FG456 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 19: **FG456 Differential Pin Pair Summary XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	W12	U12	NA	IO_DLL_L75P
1	5	Y11	AA11	NA	IO_DLL_L75N
2	1	A11	D11	NA	IO_DLL_L13P
3	0	C11	B11	NA	IO_DLL_L13N
IO LVDS Total Pairs: 119, Asynchronous Output Pairs: 69					
0	0	B3	D5	NA	-
1	0	E6	B4	√	VREF
2	0	E7	A4	NA	-
3	0	D6	C6	√	VREF
4	0	B6	A5	1	-
5	0	C7	D7	1	-
6	0	B7	E8	√	VREF
7	0	E9	A7	√	-
8	0	B8	C8	1	-
9	0	A8	D9	1	-
10	0	E10	C9	NA	-
11	0	C10	A9	√	VREF
12	0	B10	F11	2	-
13	1	D11	B11	NA	IO_LVDS_DLL
14	1	D12	C12	2	-
15	1	A13	B12	2	-
16	1	B13	E12	√	VREF
17	1	D13	C13	√	-

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
0	VCCO	H10
1	VCCO	J15
1	VCCO	J14
1	VCCO	H18
1	VCCO	H17
1	VCCO	H16
1	VCCO	H15
2	VCCO	N18
2	VCCO	M19
2	VCCO	M18
2	VCCO	L19
2	VCCO	K19
2	VCCO	J19
3	VCCO	V19
3	VCCO	U19
3	VCCO	T19
3	VCCO	R19
3	VCCO	R18
3	VCCO	P18
4	VCCO	W18
4	VCCO	W17
4	VCCO	W16
4	VCCO	W15
4	VCCO	V15
4	VCCO	V14
5	VCCO	W9
5	VCCO	W12
5	VCCO	W11
5	VCCO	W10
5	VCCO	V13
5	VCCO	V12
6	VCCO	V8
6	VCCO	U8
6	VCCO	T8
6	VCCO	R9
6	VCCO	R8
6	VCCO	P9

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
7	VCCO	N9
7	VCCO	M9
7	VCCO	M8
7	VCCO	L8
7	VCCO	K8
7	VCCO	J8
NA	GND	V25
NA	GND	V2
NA	GND	U17
NA	GND	U16
NA	GND	U15
NA	GND	U14
NA	GND	U13
NA	GND	U12
NA	GND	U11
NA	GND	U10
NA	GND	T17
NA	GND	T16
NA	GND	T15
NA	GND	T14
NA	GND	T13
NA	GND	T12
NA	GND	T11
NA	GND	T10
NA	GND	R17
NA	GND	R16
NA	GND	R15
NA	GND	R14
NA	GND	R13
NA	GND	R12
NA	GND	R11
NA	GND	R10
NA	GND	P25
NA	GND	P17
NA	GND	P16
NA	GND	P15

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
1	IO	C5
1	IO_LVDS_DLL_L29P	A19
1	IO_L30N_Y	C21
1	IO_VREF_L30P_Y	B19[2]
1	IO_L31N_Y	C19
1	IO_L31P_Y	A18
1	IO_L32N_YY	D19
1	IO_VREF_L32P_YY	B18
1	IO_L33N_YY	C18
1	IO_L33P_YY	A17
1	IO_L34N_Y	D18
1	IO_L34P_Y	B17
1	IO_L35N_Y	E18
1	IO_L35P_Y	A16
1	IO_L36N_YY	C17
1	IO_VREF_L36P_YY	D17
1	IO_L37N_YY	B16
1	IO_L37P_YY	E17
1	IO_L38N_Y	A15
1	IO_L38P_Y	C16
1	IO_L39N_Y	B15
1	IO_L39P_Y	D16
1	IO_L40N_YY	A14
1	IO_VREF_L40P_YY	B14[1]
1	IO_L41N_YY	C15
1	IO_L41P_YY	A13
1	IO_L42N_Y	D15
1	IO_L42P_Y	B13
1	IO_L43N_Y	C14
1	IO_L43P_Y	A12
1	IO_L44N_YY	D14
1	IO_L44P_YY	C13
1	IO_L45N_YY	B12
1	IO_VREF_L45P_YY	D13
1	IO_L46N_Y	A11
1	IO_L46P_Y	C12
1	IO_L47N_Y	B11
1	IO_L47P_Y	C11
1	IO_L48N_YY	A10
1	IO_VREF_L48P_YY	D11
1	IO_L49N_YY	B10
1	IO_L49P_YY	C10
1	IO_L50N_Y	A9
1	IO_VREF_L50P_Y	D10[3]
1	IO_L51N_Y	B9
1	IO_L51P_Y	C9
1	IO_L52N_YY	A8
1	IO_VREF_L52P_YY	B8
1	IO_L53N_YY	D9
1	IO_L53P_YY	A7
1	IO_L54N_Y	C8
1	IO_L54P_Y	B7
1	IO_L55N_Y	D8
1	IO_L55P_Y	A6
1	IO_L56N_YY	C7
1	IO_VREF_L56P_YY	B6
1	IO_L57N_YY	D7
1	IO_L57P_YY	A5
1	IO_L58N_Y	C6
1	IO_VREF_L58P_Y	B5[1]
1	IO_L59N_Y	D6
1	IO_L59P_Y	A4
1	IO_WRITE_L60N_YY	B4
1	IO_CS_L60P_YY	D5
2	IO	D1
2	IO	F4
2	IO_DOUT_BUSY_L61P_YY	E3
2	IO_DIN_D0_L61N_YY	C2
2	IO_L62P_Y	D3
2	IO_L62N_Y	F3
2	IO_VREF_L63P	D2[1]

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
4	IO_VREF_L132P_YY	AV8
4	IO_L132N_YY	AU9
4	IO_L133P_Y	AW8
4	IO_L133N_Y	AT10
4	IO_VREF_L134P_Y	AV9[3]
4	IO_L134N_Y	AU10
4	IO_L135P_YY	AW9
4	IO_L135N_YY	AT11
4	IO_VREF_L136P_YY	AV10
4	IO_L136N_YY	AU11
4	IO_L137P_Y	AW10
4	IO_L137N_Y	AU12
4	IO_L138P_Y	AV11
4	IO_L138N_Y	AT13
4	IO_VREF_L139P_YY	AW11
4	IO_L139N_YY	AU13
4	IO_L140P_YY	AT14
4	IO_L140N_YY	AV12
4	IO_L141P_Y	AU14
4	IO_L141N_Y	AW12
4	IO_L142P_Y	AT15
4	IO_L142N_Y	AV13
4	IO_L143P_YY	AU15
4	IO_L143N_YY	AW13
4	IO_VREF_L144P_YY	AV14[1]
4	IO_L144N_YY	AT16
4	IO_L145P_Y	AW14
4	IO_L145N_Y	AU16
4	IO_L146P_Y	AV15
4	IO_L146N_Y	AR17
4	IO_L147P_YY	AW15
4	IO_L147N_YY	AT17
4	IO_VREF_L148P_YY	AU17
4	IO_L148N_YY	AV16
4	IO_L149P_Y	AR18
4	IO_L149N_Y	AW16

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
4	IO_L150P_Y	AT18
4	IO_L150N_Y	AV17
4	IO_L151P_YY	AU18
4	IO_L151N_YY	AW17
4	IO_VREF_L152P_YY	AT19
4	IO_L152N_YY	AV18
4	IO_L153P_Y	AU19
4	IO_L153N_Y	AW18
4	IO_VREF_L154P	AU21[2]
4	IO_L154N	AV19
4	IO_LVDS_DLL_L155P	AT21
5	GCK1	AU22
5	IO	AT34
5	IO	AW20
5	IO_LVDS_DLL_L155N	AT22
5	IO_VREF_L156P_Y	AV20[2]
5	IO_L156N_Y	AR22
5	IO_L157P_YY	AV23
5	IO_VREF_L157N_YY	AW21
5	IO_L158P_YY	AU23
5	IO_L158N_YY	AV21
5	IO_L159P_Y	AT23
5	IO_L159N_Y	AW22
5	IO_L160P_Y	AR23
5	IO_L160N_Y	AV22
5	IO_L161P_YY	AV24
5	IO_VREF_L161N_YY	AW23
5	IO_L162P_YY	AW24
5	IO_L162N_YY	AU24
5	IO_L163P_Y	AW25
5	IO_L163N_Y	AT24
5	IO_L164P_Y	AV25
5	IO_L164N_Y	AU25
5	IO_L165P_YY	AW26
5	IO_VREF_L165N_YY	AT25[1]

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
1	IO	J20[5]
1	IO	L18[4]
1	IO_LVDS_DLL_L34P	E16
1	IO_L35N_YY	B16
1	IO_VREF_L35P_YY	F16[2]
1	IO_L36N_YY	A16
1	IO_L36P_YY	H16
1	IO_L37N_YY	C16
1	IO_VREF_L37P_YY	K15
1	IO_L38N_YY	K16
1	IO_L38P_YY	G16
1	IO_L39N_Y	A17
1	IO_L39P_Y	E17
1	IO_L40N_Y	F17
1	IO_L40P_Y	C17
1	IO_L41N_YY	E18
1	IO_VREF_L41P_YY	A18
1	IO_L42N_YY	D18
1	IO_L42P_YY	A19
1	IO_L43N_Y	B19
1	IO_L43P_Y	G18
1	IO_L44N_Y	D19
1	IO_L44P_Y	H18
1	IO_L45N_YY	F18
1	IO_VREF_L45P_YY	F19[1]
1	IO_L46N_YY	B20
1	IO_L46P_YY	K17
1	IO_L47N_Y	D20[4]
1	IO_L47P_Y	A20[4]
1	IO_L48N_Y	G19
1	IO_L48P_Y	C20
1	IO_L49N_Y	K18
1	IO_L49P_Y	E20
1	IO_L50N_YY	B21[4]
1	IO_L50P_YY	D21[4]
1	IO_L51N_YY	F20
1	IO_L51P_YY	A21

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
1	IO_L52N_YY	C21
1	IO_VREF_L52P_YY	A22
1	IO_L53N_YY	H19
1	IO_L53P_YY	B22
1	IO_L54N_YY	E21
1	IO_L54P_YY	D22
1	IO_L55N_YY	F21
1	IO_VREF_L55P_YY	C22
1	IO_L56N_YY	H20
1	IO_L56P_YY	E22
1	IO_L57N_Y	G21
1	IO_L57P_Y	A23
1	IO_L58N_Y	A24
1	IO_L58P_Y	K19
1	IO_L59N_YY	C24
1	IO_VREF_L59P_YY	B24
1	IO_L60N_YY	H21
1	IO_L60P_YY	G22
1	IO_L61N_Y	E23
1	IO_L61P_Y	C25
1	IO_L62N_Y	D24
1	IO_L62P_Y	A26
1	IO_L63N_YY	B26
1	IO_VREF_L63P_YY	K20
1	IO_L64N_YY	D25
1	IO_L64P_YY	J21
1	IO_L65N_Y	C26[4]
1	IO_L65P_Y	F23[4]
1	IO_L66N_Y	B27
1	IO_VREF_L66P_Y	G23[1]
1	IO_L67N_Y	A27
1	IO_L67P_Y	F24
1	IO_L68N_YY	B28[3]
1	IO_L68P_YY	A28[4]
1	IO_WRITE_L69N_YY	K21
1	IO_CS_L69P_YY	C27

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
NA	GND	AP2
NA	GND	AN3
NA	GND	AM20
NA	GND	AK30
NA	GND	AG8
NA	GND	AC29
NA	GND	Y3
NA	GND	Y32
NA	GND	W21
NA	GND	V21
NA	GND	T8
NA	GND	T27
NA	GND	R21
NA	GND	P21
NA	GND	H19
NA	GND	F29
NA	GND	C11
NA	GND	B3
NA	GND	A32
NA	GND	AP3
NA	GND	AN32
NA	GND	AM24
NA	GND	AJ6
NA	GND	AG16
NA	GND	AA14
NA	GND	Y14
NA	GND	W8
NA	GND	W27
NA	GND	U14
NA	GND	T14
NA	GND	R3
NA	GND	R32
NA	GND	M6
NA	GND	H27

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
NA	GND	E5
NA	GND	C15
NA	GND	B32
NA	GND	A33
NA	GND	AP7
NA	GND	AN33
NA	GND	AM32
NA	GND	AJ12
NA	GND	AG19
NA	GND	AA15
NA	GND	Y15
NA	GND	W14
NA	GND	V14
NA	GND	U15
NA	GND	T15
NA	GND	R14
NA	GND	P14
NA	GND	M29
NA	GND	G1
NA	GND	E18
NA	GND	C20
NA	GND	B33
NA	GND	A34
NA	GND	AP28
NA	GND	AN34
NA	GND	AM33
NA	GND	AJ23
NA	GND	AG27
NA	GND	AA16
NA	GND	Y16
NA	GND	W15
NA	GND	V15
NA	GND	U16
NA	GND	T16

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
111	2	M31	R26	2600 1600	-
112	2	N30	P28	3200 1600 1000	-
113	2	N29	N33	2600 2000 1000	VREF
114	2	T25	N34	3200 2600 2000 1600	-
115	2	P34	R27	3200 2600 2000 1600 1000	-
116	2	P29	P31	3200 2600 1600 1000	-
117	2	P33	T26	3200 2600 2000	-
118	2	R34	R28	2600 2000 1000	-
119	2	N31	N32	2000 1600 1000	D3
120	2	P30	R33	2000 1600	-
121	2	R29	T34	3200 2600 2000 1600 1000	-
122	2	R30	T30	1000	-
123	2	T28	R31	3200 1600	-
124	2	T29	U27	3200 2600 1600 1000	-
125	2	T31	T33	2000 1600 1000	VREF
126	2	U28	T32	2000 1600 1000	-
127	2	U29	U33	3200 2600 1600 1000	VREF
128	2	V33	U31	3200 2600 2000 1600 1000	-
129	3	V26	V30	3200 2600 1600 1000	VREF
130	3	W34	V28	2000 1600 1000	-
131	3	W32	W30	2000 1600 1000	VREF

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
132	3	V29	Y34	3200 2600 1600 1000	-
133	3	W29	Y33	3200 1600	-
134	3	W26	W28	1000	-
135	3	Y31	Y30	3200 2600 2000 1600 1000	-
136	3	AA34	W31	2000 1600	-
137	3	AA33	Y29	2000 1600 1000	VREF
138	3	W25	AB34	2600 2000 1000	-
139	3	Y28	AB33	3200 2600 2000	-
140	3	AA30	Y26	3200 2600 1600 1000	-
141	3	Y27	AA31	3200 2600 2000 1600 1000	-
142	3	AA27	AA29	3200 2600 2000 1600	-
143	3	AB32	AB29	2600 2000 1000	VREF
144	3	AA28	AC34	3200 1600 1000	-
145	3	Y25	AD34	2600 1600	-
146	3	AB30	AC33	3200 2600 1600 1000	-
147	3	AA26	AC32	2000 1000	-
148	3	AD33	AB28	3200 2600 2000	-
149	3	AE34	AB27	3200 2600 2000 1600 1000	D5
150	3	AE33	AC30	2000 1600 1000	VREF
151	3	AA25	AE32	3200 1600 1000	-
152	3	AE31	AD29	3200 2600 2000 1600 1000	-

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
192	4	AK24	AH23	2600 1600 1000	-
193	4	AF22	AP24	3200 2600 2000 1600 1000	VREF
194	4	AL24	AK23	3200 2600 2000 1600 1000	-
195	4	AG22	AN23	3200 1600 1000	-
196	4	AP23	AM23	3200 2000 1000	-
197	4	AH22	AP22	3200 2000 1000	-
198	4	AL23	AF21	3200 2600 1000	-
199	4	AL22	AJ22	3200 2600 2000 1600 1000	-
200	4	AK22	AM22	3200 2600 2000 1600 1000	VREF
201	4	AG21	AJ21	2000 1600	-
202	4	AP21	AE20	3200 2600 1000	-
203	4	AH21	AL21	3200 2600 1000	-
204	4	AN21	AF20	3200	-
205	4	AK21	AP20	3200 2600 2000 1600 1000	-
206	4	AE19	AN20	3200 2600 2000 1600 1000	VREF
207	4	AG20	AL20	3200 1600	-
208	4	AH20	AK20	3200 2000 1000	-
209	4	AN19	AJ20	3200 2000 1000	-
210	4	AF19	AP19	3200 2600	-

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
211	4	AM19	AH19	3200 2600 2000 1600 1000	-
212	4	AJ19	AP18	3200 2600 2000 1600 1000	VREF
213	4	AF18	AP17	2600 1600 1000	-
214	4	AJ18	AL18	2600 1600 1000	VREF
215	5	AM18	AL17	None	IO_LVDS_DLL
216	5	AH17	AM17	2600 1600 1000	VREF
217	5	AJ17	AG17	2600 1600 1000	-
218	5	AP16	AL16	3200 2600 2000 1600 1000	VREF
219	5	AJ16	AM16	3200 2600 2000 1600 1000	-
220	5	AK16	AP15	3200 2600	-
221	5	AL15	AH16	3200 2000 1000	-
222	5	AN15	AF16	3200 2000 1000	-
223	5	AP14	AE16	3200 1600	-
224	5	AK15	AJ15	3200 2600 2000 1600 1000	VREF
225	5	AH15	AN14	3200 2600 2000 1600 1000	-
226	5	AK14	AG15	3200	-
227	5	AM13	AF15	3200 2600 1000	-
228	5	AG14	AP13	3200 2600 1000	-
229	5	AE14	AE15	2000 1600	-
230	5	AN13	AG13	3200 2600 2000 1600 1000	VREF